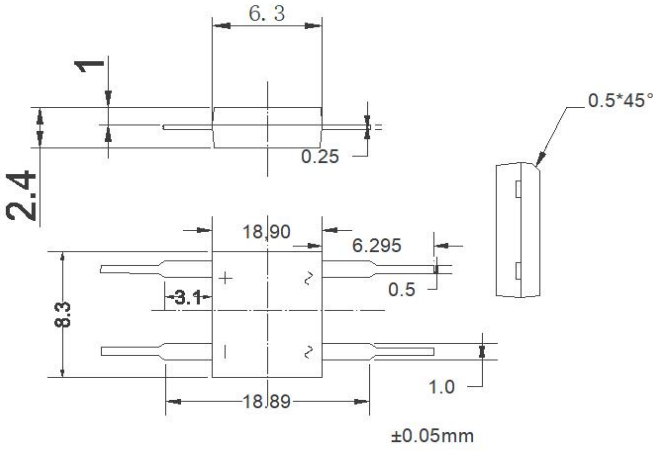


|   |   |
|---|---|
| <b>特征/Features</b> <ul style="list-style-type: none"> <li>◆ GPP芯片<br/>Glass passivated chip</li> <li>◆ 低反向漏电流<br/>Low Reverse Leakage Current</li> <li>◆ 高耐浪涌电流能力<br/>High surge current capability</li> <li>◆ 接线端与壳体间绝缘耐压2500V<br/>Case to Terminal Isolation Voltage 2500V</li> </ul> | <b>外形尺寸/Outline Dimensions</b><br><b>Case: DB Series</b><br>Dimensions in millimeters<br> |
| <b>机械参数/Mechanical Data</b>   |   |
| <ul style="list-style-type: none"> <li>◆ 本体: 塑封<br/>Case: plastic package</li> <li>◆ 标识/极性: 本体标记<br/>Marking / Polarity: Marked on Body</li> <li>◆ 重量: 约克<br/>Weight: About 0.35 grams</li> </ul>   |   |

**极限值/Maximum Ratings and Thermal Characteristics @ Ta = 25°C unless otherwise noted**

| 符号<br>Symbol                      | 特性 Characteristic   | DB3      |     |     |     |     |     |      | 单位<br>Unit       |
|-----------------------------------|---|----------|-----|-----|-----|-----|-----|------|------------------|
|                                   |   | 005      | 01  | 02  | 04  | 05  | 06  | 07   |                  |
| V <sub>RRM</sub>                  | 最大反向重复峰值电压<br>Maximum Recurrent Peak Reverse Voltage  | 50       | 100 | 200 | 400 | 600 | 800 | 1000 | V                |
| I <sub>F(AV)</sub>                | 平均整流输出电流<br>Average Forward Output Rectified Current@Ta =120°C                              | 3        |     |     |     |     |     |      | A                |
| V <sub>F</sub>                    | 正向峰值电压<br>Forward Voltage Per Leg @I <sub>FM</sub> =3.0A                                    | 1.05     |     |     |     |     |     |      | V                |
| I <sub>FSM</sub>                  | 正向浪涌电流<br>Peak Forward Surge Current 8.3ms Single Half Sine-wave superimposed on rated load | 80       |     |     |     |     |     |      | A                |
| I <sub>R</sub>                    | 反向漏电流<br>Maximum DC reverse current at rated DC blocking voltage per leg                    | 5<br>500 |     |     |     |     |     |      | uA               |
| i <sup>2</sup> t                  | 热容值<br>Rating for fusing (t<8.3ms)  | 26       |     |     |     |     |     |      | A <sup>2</sup> S |
| V <sub>isol</sub>                 | 绝缘耐压<br>Rms isolation voltage from case to leads  | 2500     |     |     |     |     |     |      | V                |
| C <sub>J</sub>                    | 典型结电容<br>Typical Junction Capacitance   | 23       |     |     |     |     |     |      | pF               |
| R <sub>θJC</sub>                  | 热阻<br>Maximum thermal resistance per leg  | 10       |     |     |     |     |     |      | °C/W             |
| T <sub>j</sub> , T <sub>STG</sub> | 结温, 存储条件<br>Operating Junction and storage temperature range                                | -55~150  |     |     |     |     |     |      | °C               |

Note:  
 (1) Junction to case with heatsink  
 (2) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with M3 screw .

#### ◆ 特性曲线 (典型) Characteristics(Typical)

Fig 1-forwardCurrent derating Curve  
图1正向电流降额曲线

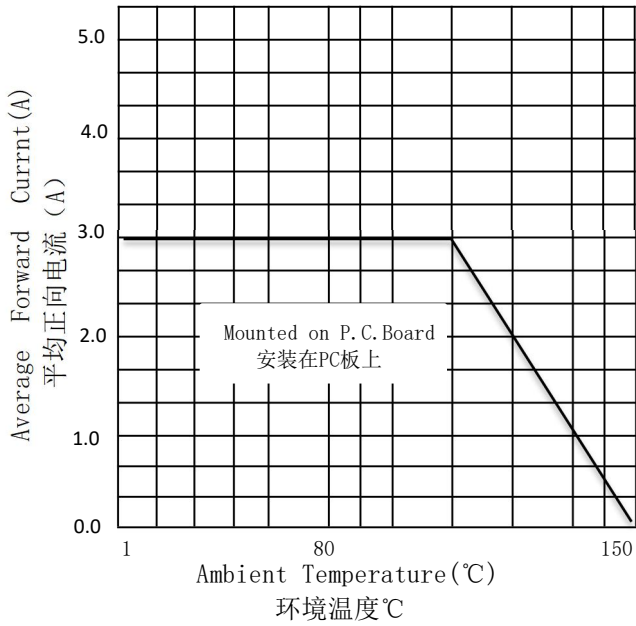


Fig.2-Maximum Non-Repetitive Surge Current  
图2 最大不重复正向浪涌曲线

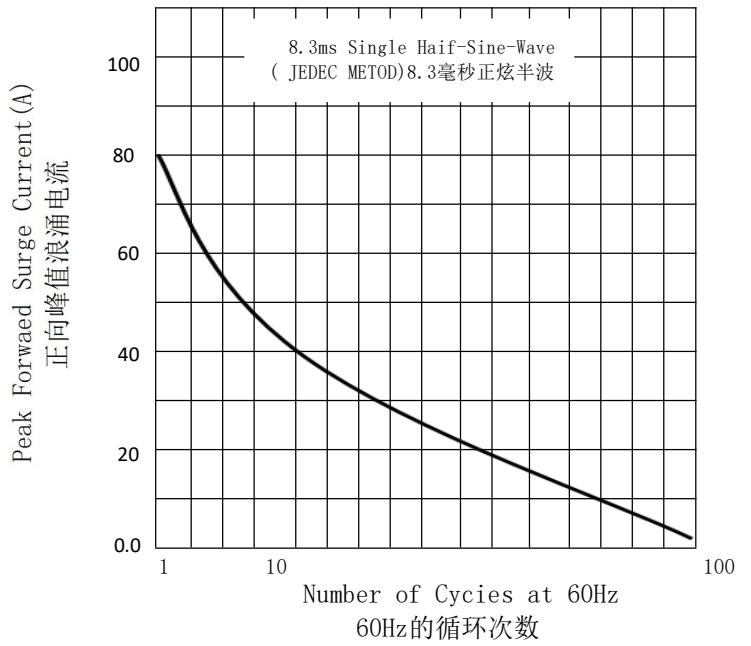


Fig.3-Typical Reverse Characteristics  
图3. 典型的反向特性

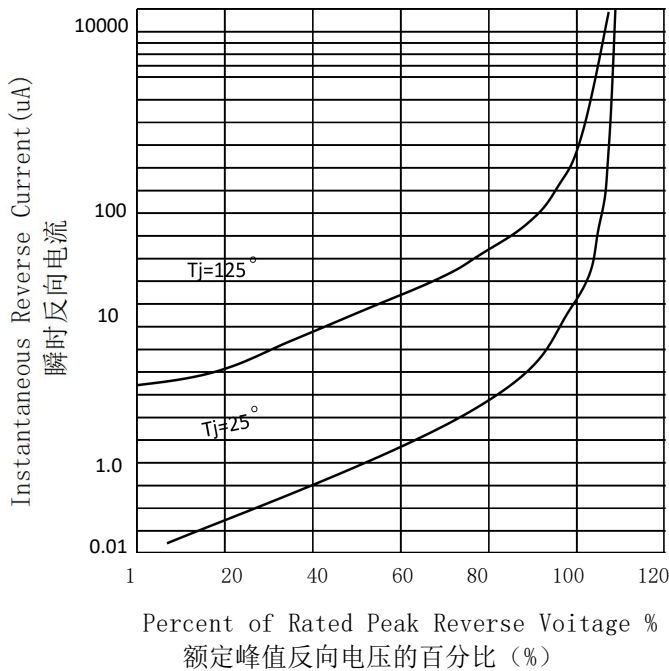


Fig.4-Typical Forwaed Characteristics  
图4. 典型的正向特性

